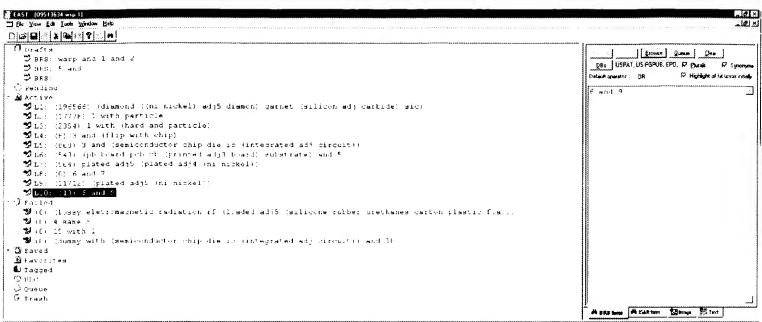
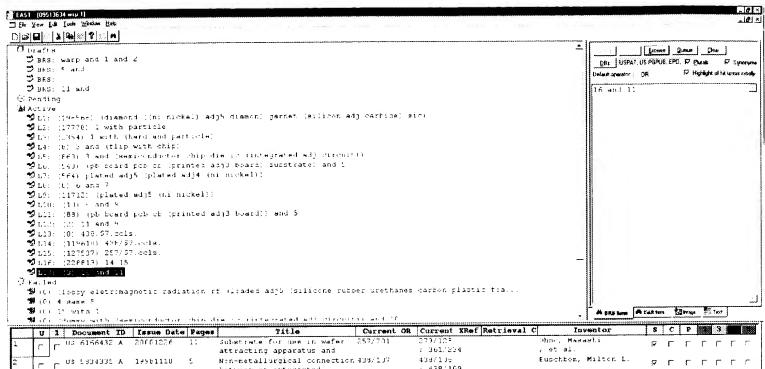


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L		1.6	.3 100500 .1	3465		F1	Surretrate material for withhing a semi-conductor			ramajata kili Ali, rajaka			•	-		
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10		$T^{-\frac{10}{\Delta}}$.: 151101 1	1653			FLAMED CHECKE SOURSE AM FOR HIGH POWER MNICE			LARSON, SAMLEY 1	ſ•	ı	ſ	1	f I	
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1	۲	4 [.	υβ 2001003 A1	1345			Laminated radiation member, power semiconductor			Araki, Kiyeshi , Kida, Masahiro	Æ	۲	r	Г	Γ	ГГ
2	г	Γ	US 6105874	В1	20010206		Substrate material for mounting a semiconduitor	428 472	4287325 : 4287305	Yamagata, Shinichi , + el.	P	٢	r	r	Г	
3	f***	1"	03 6117493	A	20010912		Micro texture media made by polishing of a selectively	427 (5.33	437/138 : 427/130	Wong, Javier , et al.	ju	٢	r	ľ	f"	t t.
4	г	Γ	US 6054103	A	20000425		Method for making CVD diamond coated substrate for	427, 249, 8	427 122 : 437/249:11	Zimmer, Jerry W.	₽	Γ	г	٢	Γ	ГГ
5	٣	٣	UJ 5930722	A	19991109		Flated aluminum alloy, cylinder block thereof,	205/213	205/640	Kuroda, Tetsuya , et al.	P	۲	r	٣	r	г г
5	r	٣	us 5921856	A	19990713		CVD diamond coated substrate for polishing pad	451/539	451/506	Zimmer, Jerry W.	Þ	r	r	٣	r	гг
7	٢	Γ	U3 5759667	A	19980602		Diamond wire drawing die and process for manufacturing	428, 132	429 131 ; 488,212	Takahashi, Toshiya , et al.	₽	۲	Γ	٢	٢	г ŗ.
8	۲	٢	us 5571236	A	19961105	9	Diamond wire drawing die	72/467		Takahashi, Toshiya , et al.	(~	ſ	٢	٢	٢	ГГ
ÿ	г	Γ	U\$ 5275782	A	19951228		Coated parts with film having powder-skeleton	427, 242	235.83 ; 407/11	Sagawa, Masato , et el.	F	r	۲	Γ	۲	гг
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2	Г	- '	L ns F834335 Y	19961110 5	Non-metallurgical connection between an integrated	t 438/1J7	438/10s; 438/169	Euschbom, Milton L.	₽	٢	r	r r	٢	_
3	r	•••	m U3 4979019 A	19901218 26	6 Frinted direuit board with inorganic insulating matrix		174/258 ; 174/35R	Paquetre, Edward L. , et al.	Þ	٣	t.	r r	1	٢
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